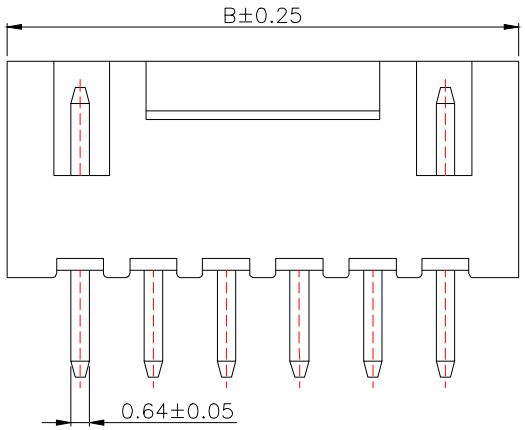
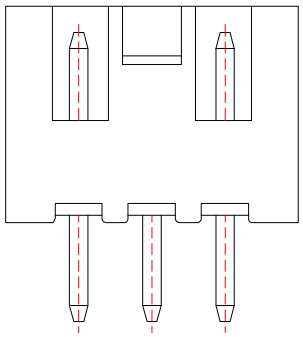
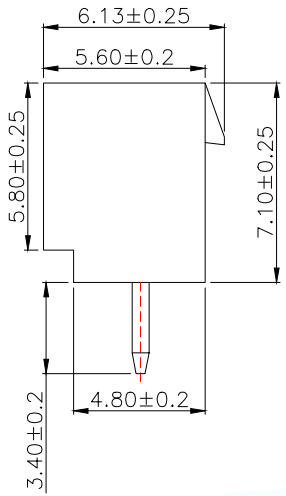
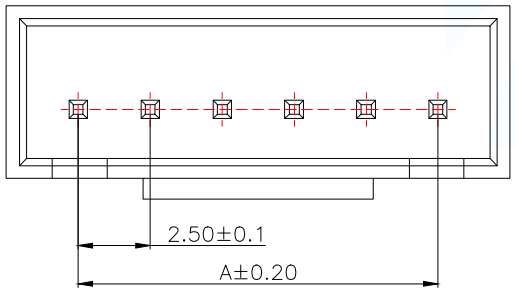
ROHS Compliant

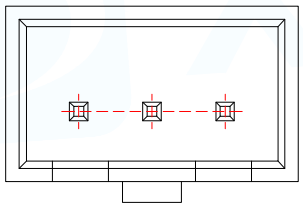
MAPX	MODIFICATION	DATE	DRAW	APPROVE



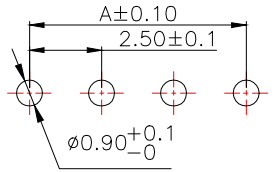








Part No	Pin	A	B
WAFER-HA2.54-2PZZ	2	2.50	7.50
WAFER-HA2.54-3PZZ	3	5.00	10.00
WAFER-HA2.54-4PZZ	4	7.50	12.50
WAFER-HA2.54-5PZZ	5	10.00	15.00
WAFER-HA2.54-6PZZ	6	12.50	17.50
WAFER-HA2.54-7PZZ	7	15.00	20.00
WAFER-HA2.54-8PZZ	8	17.50	22.50
WAFER-HA2.54-9PZZ	9	20.00	25.00
WAFER-HA2.54-10PZZ	10	22.50	27.50
WAFER-HA2.54-11PZZ	11	25.00	30.00
WAFER-HA2.54-12PZZ	12	27.50	32.50
WAFER-HA2.54-13PZZ	13	30.00	35.00
WAFER-HA2.54-14PZZ	14	32.50	37.50
WAFER-HA2.54-15PZZ	15	35.00	40.00
WAFER-HA2.54-16PZZ	16	37.50	42.50
WAFER-HA2.54-17PZZ	17	40.00	45.00
WAFER-HA2.54-18PZZ	18	42.50	47.50
WAFER-HA2.54-19PZZ	19	45.00	50.00
WAFER-HA2.54-20PZZ	20	47.50	52.50



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:
1.塑件材料:PA66(UL-94V-0)
2.接触件:黄铜镀锡
3.接触电阻:≤10mΩ
4.绝缘电阻:≥100MΩ
5.额定电压:250V AC DC
6.额定电流:2.0A AC DC
7.耐压:能承受1000V AC/Minute
8.工作温度:-25°~+85°
9.可焊性试验:浸锡面积≥95%温度235±5°,时间2.5±0.5秒
10.铅和镉等六大有害物质含量要符合环保要求.

序号	名称	材料	数量	备注
2	端子Contact	黄铜	N*1	电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN
1	基座Wafer	PA66(UL94 V-0)	1	白色

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co,Ltd

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS:	ANGLES:
.X±0.20	±2°
.XX±0.10	
.XXX±0.05	

CUSTOMER COPY

TITLE: WAFER HA2.54MM 带扣 直针

PAR	WAFER-HA2.54-NPZZ	
DWN		
CHKD		
APVD		
SCALE1:1	UNIT:MM	
SIZE:A4	SHEET:1F1	REV:A